CMOS Digital Integrated Circuits Silicon Monolithic

74VHC595FT

1. Functional Description

- 8-Bit Shift Register/Latch (3-state)

2. General

The 74VHC595FT is an advanced high speed 8-BIT SHIFT REGISTER/LATCH fabricated with silicon gate C^2MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

The 74VHC595FT contains an 8-bit static shift register which feeds an 8-bit storage register.

Shift operation is accomplished on the positive going transition of the SCK input. The output register is loaded with the contents of the shift register on the positive going transition of the RCK input.

Since RCK and SCK signal are independent, parallel outputs can be held stable during the shift operation. And, since the parallel outputs are 3-state, it can be directly connected to 8-bit bus. This register can be used in serial-to-parallel conversion, data receivers, etc.

An input protection circuit ensures that 0 to 5.5 V can be applied to the input pins without regard to the supply voltage. This device can be used to interface 5 V to 3 V systems and two supply systems such as battery back up. This circuit prevents device destruction due to mismatched supply and input voltages.

3. Features

(1) AEC-Q100 (Rev. H) (Note 1)

(2) Wide operating temperature range: T_{opr} = -40 to 125 °C

(3) High speed: f_{MAX} = 185 MHz (typ.) at V_{CC} = 5.0 V

(4) Low power dissipation: I_{CC} = 4.0 μA (max) at T_a = 25°C

(5) High noise immunity: $V_{NIH} = V_{NIL}$ = 28 % V_{CC} (min)

(6) Power-down protection is provided on all inputs.

(7) Balanced propagation delays: $t_{PLH} \approx t_{PHL}$

(8) Wide operating voltage range: $V_{CC(opr)}$ = 2.0 V to 5.5 V

(9) Low noise: V_{OLP} = 1.0 V (max)

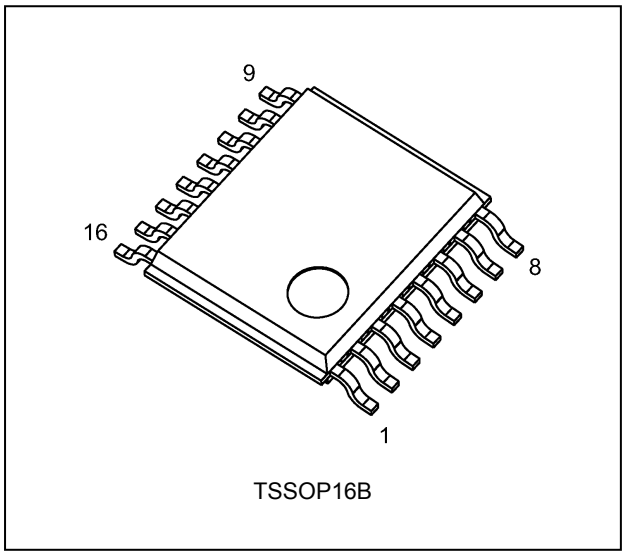
(10) Pin and function compatible with the 74 series (74AC/HC/AHC/LV etc.) 595 type.

Note 1: This device is compliant with the reliability requirements of AEC-Q100. For details, contact your Toshiba sales representative.

Start of commercial production
2013-05

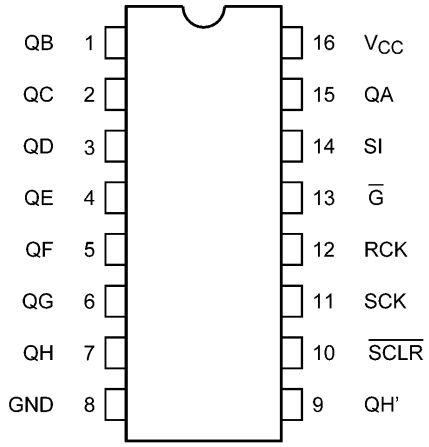
2026-05-13
Rev.6.0.B

4. Packaging



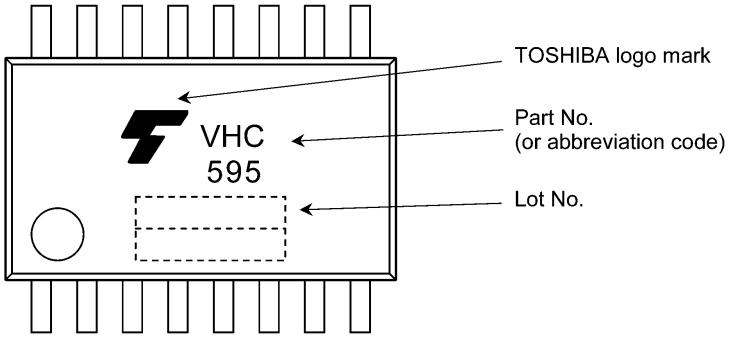
TSSOP16B

5. Pin Assignment

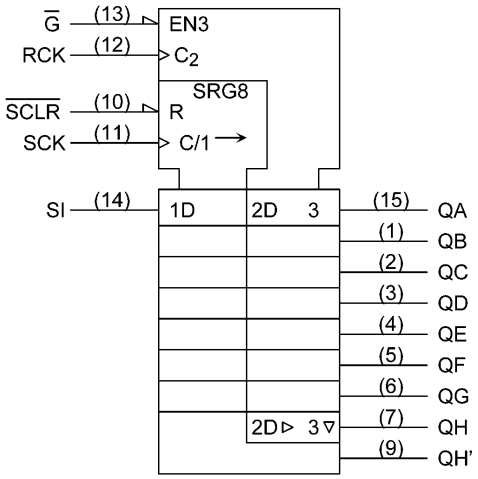


(top view)

6. Marking



7. IEC Logic Symbol

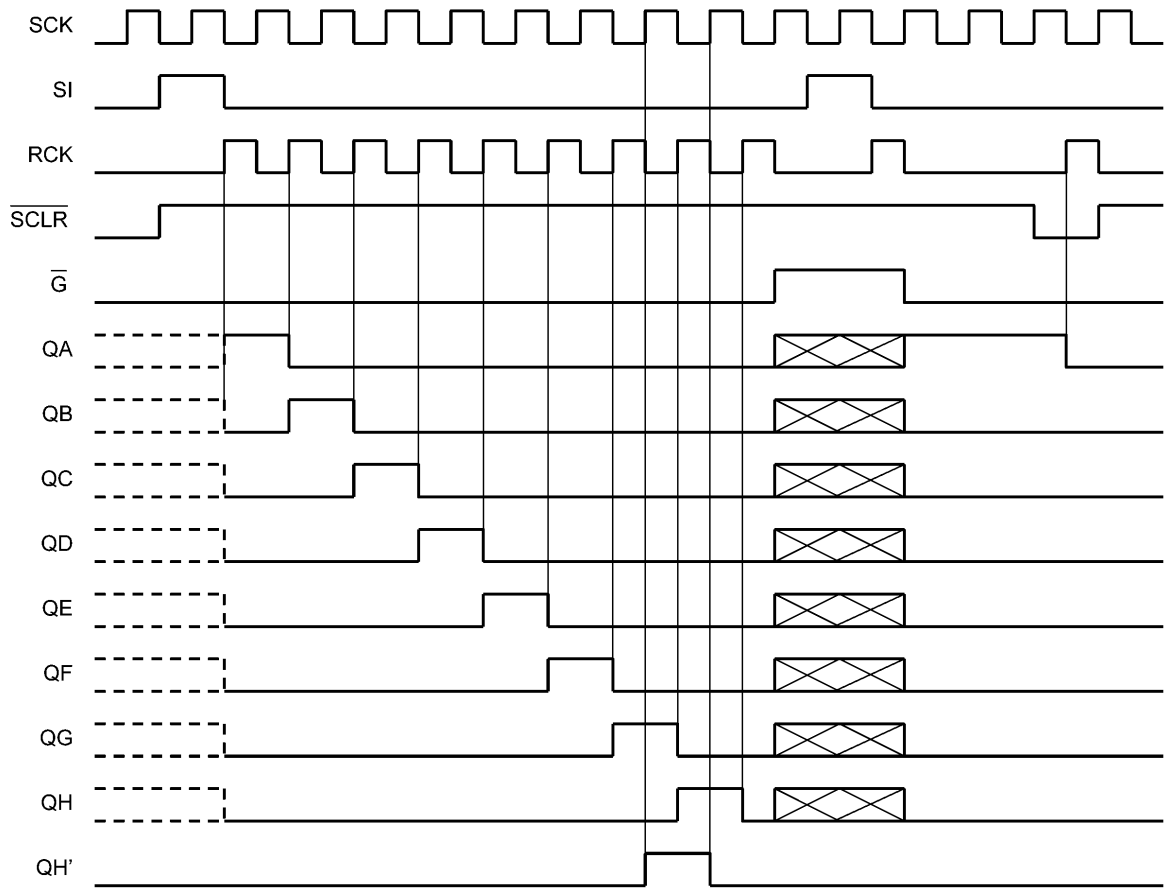


8. Truth Table

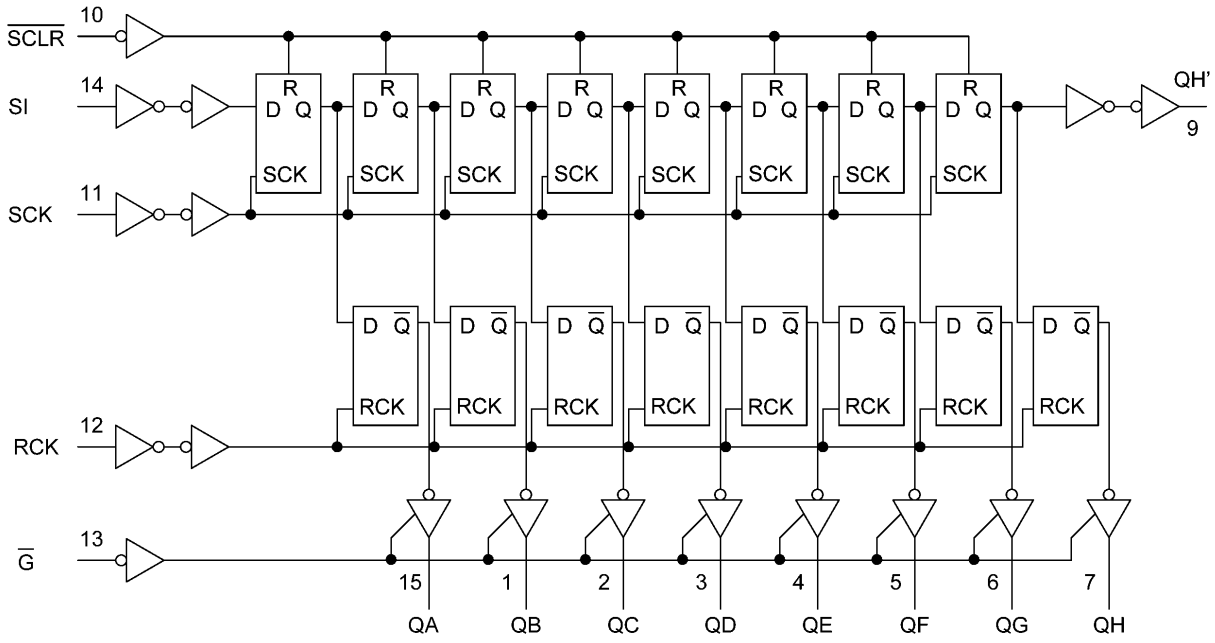
Inputs					Function
SI	SCK	$\overline{SCLR}$	RCK	$\overline{G}$	
X	X	X	X	H	QA thru QH outputs disable
X	X	X	X	L	QA thru QH outputs enable
X	X	L	X	X	Shift register is cleared.
L	↑	H	X	X	First stage of S.R. becomes “L”. Other stages store the data of previous stage, respectively.
H	↑	H	X	X	First stage of S.R. becomes “H”. Other stages store the data of previous stage, respectively.
X	↓	H	X	X	State of S.R. is not changed.
X	X	X	↑	X	S.R. data is stored into storage register.
X	X	X	↓	X	Storage register stage is not changed.

X: Don't care

9. Timing Chart



10. System Diagram



11. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Note	Rating	Unit
Supply voltage	V_{CC}		-0.5 to 7.0	V
Input voltage	V_{IN}		-0.5 to 7.0	V
Output voltage	V_{OUT}		-0.5 to V_{CC} + 0.5	V
Input diode current	I_{IK}		-20	mA
Output diode current	I_{OK}		±20	mA
Output current	I_{OUT}		±25	mA
V_{CC}/ground current	I_{CC}		±75	mA
Power dissipation	P_D	(Note 1)	180	mW
Storage temperature	T_{stg}		-65 to 150	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: 180 mW in the range of T_a = -40 to 85 °C. From T_a = 85 to 125 °C a derating factor of -3.25 mW/°C shall be applied until 50 mW.

12. Operating Ranges (Note)

Characteristics	Symbol	Test Condition	Rating	Unit
Supply voltage	V_{CC}		2.0 to 5.5	V
Input voltage	V_{IN}		0 to 5.5	V
Output voltage	V_{OUT}		0 to V_{CC}	V
Operating temperature	T_{opr}		-40 to 125	°C
Input rise and fall times	dt/dv	V_{CC} = 3.3 ± 0.3 V	0 to 100	ns/V
		V_{CC} = 5.0 ± 0.5 V	0 to 20	

Note: The operating ranges must be maintained to ensure the normal operation of the device.
Unused inputs must be tied to either V_{CC} or GND.

13. Electrical Characteristics

13.1. DC Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition		V_{CC} (V)	Min	Typ.	Max	Unit
High-level input voltage	V_{IH}	—		2.0	1.50	—	—	V
				3.0 to 5.5	V_{CC} × 0.7	—	—	
Low-level input voltage	V_{IL}	—		2.0	—	—	0.50	V
				3.0 to 5.5	—	—	V_{CC} × 0.3	
High-level output voltage	V_{OH}	V_{IN} = V_{IH} or V_{IL}	I_{OH} = -50 μA	2.0	1.9	2.0	—	V
				3.0	2.9	3.0	—	
				4.5	4.4	4.5	—	
			I_{OH} = -4 mA	3.0	2.58	—	—	
			I_{OH} = -8 mA	4.5	3.94	—	—	
Low-level output voltage	V_{OL}	V_{IN} = V_{IH} or V_{IL}	I_{OL} = 50 μA	2.0	—	0.0	0.1	V
				3.0	—	0.0	0.1	
				4.5	—	0.0	0.1	
			I_{OL} = 4 mA	3.0	—	—	0.36	
			I_{OL} = 8 mA	4.5	—	—	0.36	
3-state output OFF-state leakage current	I_{OZ}	V_{IN} = V_{IH} or V_{IL} V_{OUT} = V_{CC} or GND		5.5	—	—	±0.25	μA
Input leakage current	I_{IN}	V_{IN} = 5.5 V or GND		0 to 5.5	—	—	±0.1	μA
Quiescent supply current	I_{CC}	V_{IN} = V_{CC} or GND		5.5	—	—	4.0	μA

13.2. DC Characteristics (Unless otherwise specified, T_a = -40 to 85 °C)

Characteristics	Symbol	Test Condition		V_{CC} (V)	Min	Max	Unit
High-level input voltage	V_{IH}	—		2.0	1.50	—	V
				3.0 to 5.5	V_{CC} × 0.7	—	
Low-level input voltage	V_{IL}	—		2.0	—	0.50	V
				3.0 to 5.5	—	V_{CC} × 0.3	
High-level output voltage	V_{OH}	V_{IN} = V_{IH} or V_{IL}	I_{OH} = -50 μA	2.0	1.9	—	V
				3.0	2.9	—	
				4.5	4.4	—	
			I_{OH} = -4 mA	3.0	2.48	—	
			I_{OH} = -8 mA	4.5	3.80	—	
Low-level output voltage	V_{OL}	V_{IN} = V_{IH} or V_{IL}	I_{OL} = 50 μA	2.0	—	0.1	V
				3.0	—	0.1	
				4.5	—	0.1	
			I_{OL} = 4 mA	3.0	—	0.44	
			I_{OL} = 8 mA	4.5	—	0.44	
3-state output OFF-state leakage current	I_{OZ}	V_{IN} = V_{IH} or V_{IL} V_{OUT} = V_{CC} or GND		5.5	—	±2.50	μA
Input leakage current	I_{IN}	V_{IN} = 5.5 V or GND		0 to 5.5	—	±1.0	μA
Quiescent supply current	I_{CC}	V_{IN} = V_{CC} or GND		5.5	—	40.0	μA

13.3. DC Characteristics (Unless otherwise specified, T_a = -40 to 125 °C)

Characteristics	Symbol	Test Condition		V_{CC} (V)	Min	Max	Unit
High-level input voltage	V_{IH}	—		2.0	1.50	—	V
				3.0 to 5.5	V_{CC} × 0.7	—	
Low-level input voltage	V_{IL}	—		2.0	—	0.50	V
				3.0 to 5.5	—	V_{CC} × 0.3	
High-level output voltage	V_{OH}	V_{IN} = V_{IH} or V_{IL}	I_{OH} = -50 μA	2.0	1.9	—	V
				3.0	2.9	—	
				4.5	4.4	—	
			I_{OH} = -4 mA	3.0	2.40	—	
			I_{OH} = -8 mA	4.5	3.70	—	
Low-level output voltage	V_{OL}	V_{IN} = V_{IH} or V_{IL}	I_{OL} = 50 μA	2.0	—	0.1	V
				3.0	—	0.1	
				4.5	—	0.1	
			I_{OL} = 4 mA	3.0	—	0.55	
			I_{OL} = 8 mA	4.5	—	0.55	
3-state output OFF-state leakage current	I_{OZ}	V_{IN} = V_{IH} or V_{IL} V_{OUT} = V_{CC} or GND		5.5	—	±10.0	μA
Input leakage current	I_{IN}	V_{IN} = 5.5 V or GND		0 to 5.5	—	±2.0	μA
Quiescent supply current	I_{CC}	V_{IN} = V_{CC} or GND		5.5	—	80.0	μA

13.4. Timing Requirements (Unless otherwise specified, T_a = 25°C, Input: t_r = t_f = 3 ns)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Limit	Unit
Minimum pulse width (SCK, RCK)	$t_{w(L)}$,$t_{w(H)}$	—	3.3 ± 0.3	5.0	ns
			5.0 ± 0.5	5.0	
Minimum pulse width ($\overline{SCLR}$)	$t_{w(L)}$	—	3.3 ± 0.3	5.0	
			5.0 ± 0.5	5.0	
Minimum setup time (SI-SCK)	t_s	—	3.3 ± 0.3	3.5	ns
			5.0 ± 0.5	3.0	
Minimum setup time (SCK - RCK)	t_s	—	3.3 ± 0.3	8.0	
			5.0 ± 0.5	5.0	
Minimum setup time ($\overline{SCLR}$ -RCK)	t_s	—	3.3 ± 0.3	8.0	
			5.0 ± 0.5	5.0	
Minimum hold time (SI-SCK)	t_h	—	3.3 ± 0.3	1.5	ns
			5.0 ± 0.5	2.0	
Minimum hold time (SCK-RCK)	t_h	—	3.3 ± 0.3	0	
			5.0 ± 0.5	0	
Minimum hold time ($\overline{SCLR}$-RCK)	t_h	—	3.3 ± 0.3	0	
			5.0 ± 0.5	0	
Minimum removal time ($\overline{SCLR}$)	t_{rem}	—	3.3 ± 0.3	3.0	ns
			5.0 ± 0.5	2.5	

13.5. Timing Requirements (Unless otherwise specified, T_a = -40 to 85°C, Input: $t_r = t_f$ = 3 ns)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Limit	Unit
Minimum pulse width (SCK, RCK)	$t_{w(L)}$,$t_{w(H)}$	—	3.3 ± 0.3	5.0	ns
			5.0 ± 0.5	5.0	
Minimum pulse width ($\overline{SCLR}$)	$t_{w(L)}$	—	3.3 ± 0.3	5.0	
			5.0 ± 0.5	5.0	
Minimum setup time (SI-SCK)	t_S	—	3.3 ± 0.3	3.5	ns
			5.0 ± 0.5	3.0	
Minimum setup time (SCK - RCK)	t_S	—	3.3 ± 0.3	8.5	
			5.0 ± 0.5	5.0	
Minimum setup time ($\overline{SCLR}$ -RCK)	t_S	—	3.3 ± 0.3	9.0	
			5.0 ± 0.5	5.0	
Minimum hold time (SI-SCK)	t_h	—	3.3 ± 0.3	1.5	ns
			5.0 ± 0.5	2.0	
Minimum hold time (SCK-RCK)	t_h	—	3.3 ± 0.3	0	
			5.0 ± 0.5	0	
Minimum hold time ($\overline{SCLR}$-RCK)	t_h	—	3.3 ± 0.3	0	
			5.0 ± 0.5	0	
Minimum removal time ($\overline{SCLR}$)	t_{rem}	—	3.3 ± 0.3	3.0	ns
			5.0 ± 0.5	2.5	

13.6. Timing Requirements (Unless otherwise specified, T_a = -40 to 125 °C, Input: $t_r = t_f$ = 3 ns)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Limit	Unit
Minimum pulse width (SCK, RCK)	$t_{w(L)}$,$t_{w(H)}$	—	3.3 ± 0.3	5.0	ns
			5.0 ± 0.5	5.0	
Minimum pulse width ($\overline{SCLR}$)	$t_{w(L)}$	—	3.3 ± 0.3	5.0	
			5.0 ± 0.5	5.0	
Minimum setup time (SI-SCK)	t_S	—	3.3 ± 0.3	4.5	ns
			5.0 ± 0.5	3.5	
Minimum setup time (SCK - RCK)	t_S	—	3.3 ± 0.3	9.0	
			5.0 ± 0.5	5.0	
Minimum setup time ($\overline{SCLR}$ -RCK)	t_S	—	3.3 ± 0.3	10.0	
			5.0 ± 0.5	5.5	
Minimum hold time (SI-SCK)	t_h	—	3.3 ± 0.3	1.5	ns
			5.0 ± 0.5	2.0	
Minimum hold time (SCK-RCK)	t_h	—	3.3 ± 0.3	0	
			5.0 ± 0.5	0	
Minimum hold time ($\overline{SCLR}$ -RCK)	t_h	—	3.3 ± 0.3	0	
			5.0 ± 0.5	0	
Minimum removal time ($\overline{SCLR}$)	t_{rem}	—	3.3 ± 0.3	4.0	ns
			5.0 ± 0.5	3.0	

13.7. AC Characteristics (Unless otherwise specified, T_a = 25 °C, Input: $t_r = t_f$ = 3 ns)

Characteristics	Symbol	Note	Test Condition	V_{CC} (V)	C_L (pF)	Min	Typ.	Max	Unit
Propagation delay time (SCK-QH')	t_{PLH},t_{PHL}		—	3.3 ± 0.3	15	—	8.8	13.0	ns
					50	—	11.3	16.5	
				5.0 ± 0.5	15	—	6.2	8.2	
					50	—	7.7	10.2	
Propagation delay time ($\overline{SCLR}$ -QH')	t_{PHL}		—	3.3 ± 0.3	15	—	8.4	12.8	ns
					50	—	10.9	16.3	
				5.0 ± 0.5	15	—	5.9	8.0	
					50	—	7.4	10.0	
Propagation delay time (RCK-Q_n)	t_{PLH},t_{PHL}		—	3.3 ± 0.3	15	—	7.7	11.9	ns
					50	—	10.2	15.4	
				5.0 ± 0.5	15	—	5.4	7.4	
					50	—	6.9	9.4	
3-state output enable time	t_{PZL},t_{PZH}		R_L = 1 kΩ	3.3 ± 0.3	15	—	7.5	11.5	ns
					50	—	9.0	15.0	
				5.0 ± 0.5	15	—	4.8	8.6	
					50	—	8.3	10.6	
3-state output disable time	t_{PLZ},t_{PHZ}		R_L = 1 kΩ	3.3 ± 0.3	50	—	12.1	15.7	ns
				5.0 ± 0.5	50	—	7.6	10.3	
Maximum clock frequency	f_{MAX}		—	3.3 ± 0.3	15	80	150	—	MHz
					50	55	130	—	
				5.0 ± 0.5	15	135	185	—	
					50	95	155	—	
Input capacitance	C_{IN}		—			—	4	10	pF
Output capacitance	C_{OUT}		—			—	6	—	
Power dissipation capacitance	C_{PD}	(Note 1)	—			—	87	—	

Note 1: C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation.

$I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}$

13.8. AC Characteristics
(Unless otherwise specified, T_a = -40 to 85 °C, Input: $t_r = t_f$ = 3 ns)

Characteristics	Symbol	Test Condition	V_{CC} (V)	C_L (pF)	Min	Max	Unit
Propagation delay time (SCK-QH')	t_{PLH},t_{PHL}	—	3.3 ± 0.3	15	1.0	15.0	ns
				50	1.0	18.5	
			5.0 ± 0.5	15	1.0	9.4	
				50	1.0	11.4	
Propagation delay time ($\overline{SCLR}$ -QH')	t_{PHL}	—	3.3 ± 0.3	15	1.0	13.7	ns
				50	1.0	17.2	
			5.0 ± 0.5	15	1.0	9.1	
				50	1.0	11.1	
Propagation delay time (RCK-Q_n)	t_{PLH},t_{PHL}	—	3.3 ± 0.3	15	1.0	13.5	ns
				50	1.0	17.0	
			5.0 ± 0.5	15	1.0	8.5	
				50	1.0	10.5	
3-state output enable time	t_{PZL},t_{PZH}	R_L = 1 kΩ	3.3 ± 0.3	15	1.0	13.5	ns
				50	1.0	17.0	
			5.0 ± 0.5	15	1.0	10.0	
				50	1.0	12.0	
3-state output disable time	t_{PLZ},t_{PHZ}	R_L = 1 kΩ	3.3 ± 0.3	50	1.0	16.2	ns
			5.0 ± 0.5	50	1.0	11.0	
Maximum clock frequency	f_{MAX}	—	3.3 ± 0.3	15	70	—	MHz
				50	50	—	
			5.0 ± 0.5	15	115	—	
				50	85	—	
Input capacitance	C_{IN}	—			—	10	pF

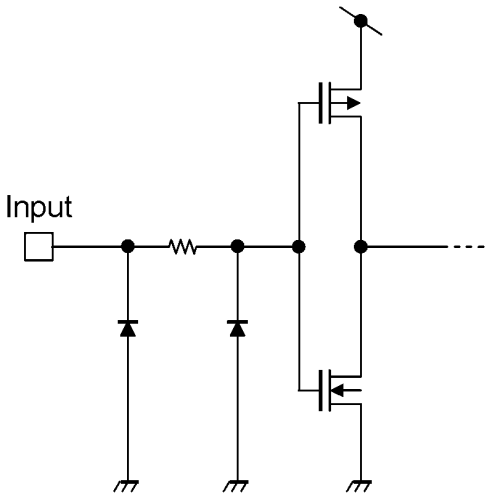
13.9. AC Characteristics (Unless otherwise specified, T_a = -40 to 125 °C, Input: $t_r = t_f$ = 3 ns)

Characteristics	Symbol	Test Condition	V_{CC} (V)	C_L (pF)	Min	Max	Unit
Propagation delay time (SCK-QH')	t_{PLH},t_{PHL}	—	3.3 ± 0.3	15	1.0	17.5	ns
				50	1.0	21.0	
			5.0 ± 0.5	15	1.0	11.0	
				50	1.0	13.0	
Propagation delay time ($\overline{SCLR}$ -QH')	t_{PHL}	—	3.3 ± 0.3	15	1.0	17.0	ns
				50	1.0	20.5	
			5.0 ± 0.5	15	1.0	10.5	
				50	1.0	12.5	
Propagation delay time (RCK-Q_n)	t_{PLH},t_{PHL}	—	3.3 ± 0.3	15	1.0	16.0	ns
				50	1.0	19.5	
			5.0 ± 0.5	15	1.0	10.0	
				50	1.0	12.0	
3-state output enable time	t_{PZL},t_{PZH}	R_L = 1 kΩ	3.3 ± 0.3	15	1.0	15.5	ns
				50	1.0	19.0	
			5.0 ± 0.5	15	1.0	11.5	
				50	1.0	13.5	
3-state output disable time	t_{PLZ},t_{PHZ}	R_L = 1 kΩ	3.3 ± 0.3	50	1.0	20.0	ns
			5.0 ± 0.5	50	1.0	13.0	
Maximum clock frequency	f_{MAX}	—	3.3 ± 0.3	15	60	—	MHz
				50	40	—	
			5.0 ± 0.5	15	105	—	
				50	75	—	
Input capacitance	C_{IN}	—			—	10	pF

13.10. Noise Characteristics (Unless otherwise specified, T_a = 25°C, Input: $t_r = t_f$ = 3 ns)

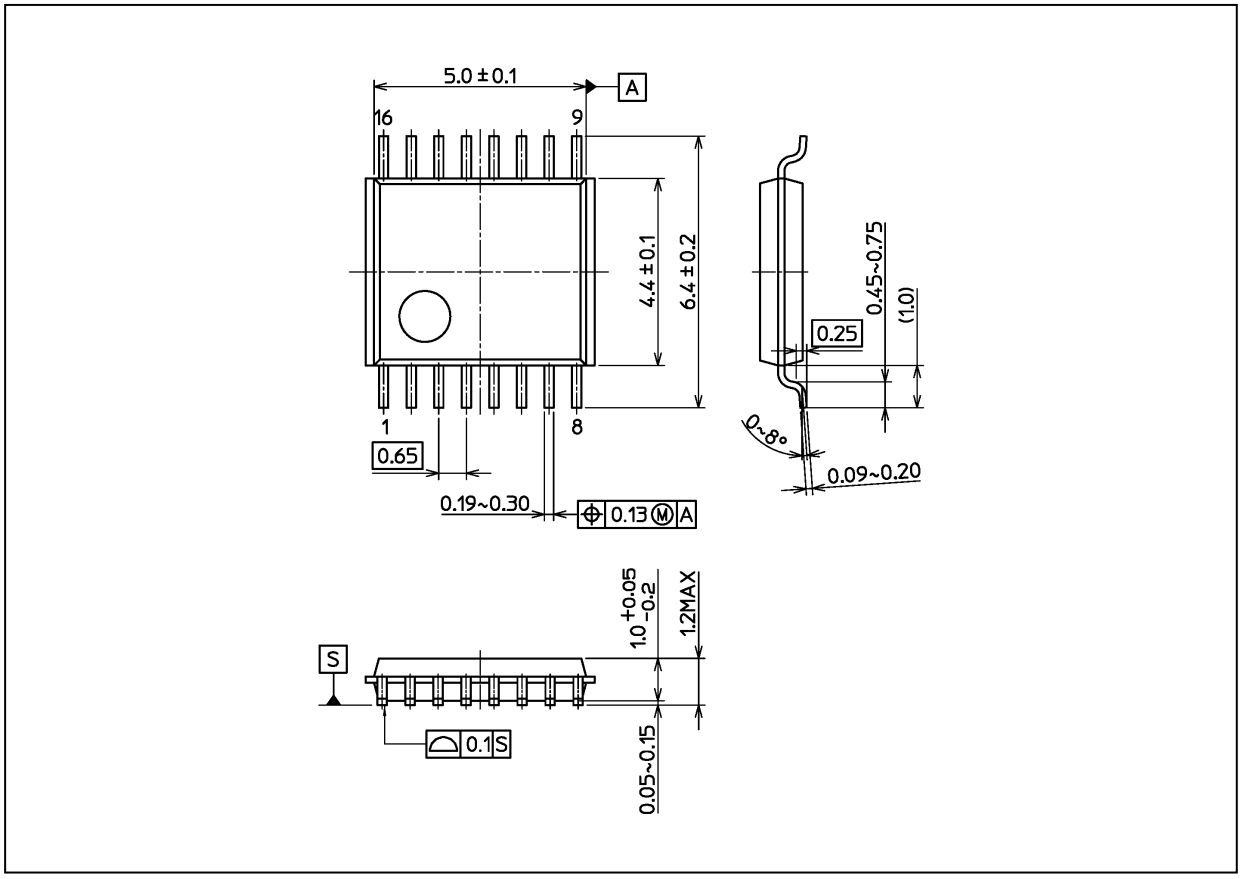
Characteristics	Symbol	Test Condition	V_{CC} (V)	Typ.	Limit	Unit
Quiet output maximum dynamic V_{OL}	V_{OLP}	C_L = 50 pF	5.0	0.8	1.0	V
Quiet output minimum dynamic V_{OL}	V_{OLV}	C_L = 50 pF	5.0	-0.8	-1.0	
Minimum high-level dynamic input voltage	V_{IHD}	C_L = 50 pF	5.0	—	3.5	
Maximum low-level dynamic input voltage	V_{ILD}	C_L = 50 pF	5.0	—	1.5	

14. Input Equivalent Circuit



Package Dimensions

Unit: mm



Weight: 0.055 g (typ.)

Package Name(s)
Nickname: TSSOP16B

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